

1 Channel High Side Switch ICs

1.5A Current Limit High Side Switch ICs

BD82000FVJ-LB BD82001FVJ-LB

General Description

This product guarantees long time support in Industrial market.
Single channel high side switch IC for USB port is a high side switch having over-current protection used in power supply line of universal serial bus (USB). N-channel power MOSFET of low on resistance and low supply current are realized in this IC.
And, over-current detection circuit, thermal shutdown circuit, under-voltage lockout and soft start circuit are built in.

Key Specifications

- Input voltage range: 2.7V to 5.5V
- ON resistance : 70mΩ(Typ.)
- Over current threshold: 1.0A min., 2.0A max.
- Number of channels: 1ch
- Standby current: 0.01μA (Typ.)
- Operating temperature range: -40°C to +85°C

Package W(Typ.) D(Typ.) H (Max.)
SOP-J8 3.00mm x 4.90mm x 1.10mm

Features

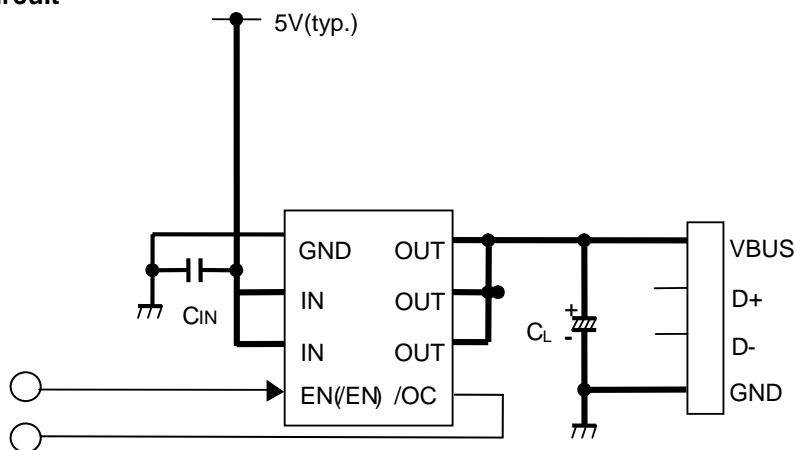
- Long time support a product for Industrial applications.
- Low On-Resistance 70mΩ MOSFET Switch
- Current limit threshold 1.5A
- Control Input Logic
 - Active "Low" Control Logic: BD82000FVJ
 - Active "High" Control Logic: BD82001FVJ
- Soft-Start Circuit
- Over-Current Protection
- Thermal Shutdown
- Under-Voltage Lockout
- Open-Drain Error Flag Output
- TTL Enable Input
- 0.8ms Typical Rise Time



Applications

Industrial Equipment, PC, PC peripheral equipment, USB hub in consumer appliances, Car accessory, and so forth

Typical Application Circuit

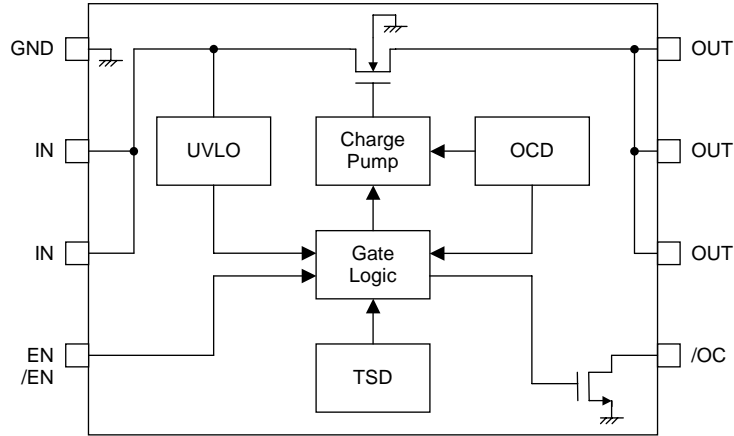


Lineup

Over current detection			Control input logic	Package		Orderable Part Number
Min.	Typ.	Max.				
1.0A	1.5A	2.0A	Low	TSSOP-B8J	Reel of 2500	BD82000FVJ-LBE2
1.0A	1.5A	2.0A	High	TSSOP-B8J	Reel of 2500	BD82001FVJ-LBE2

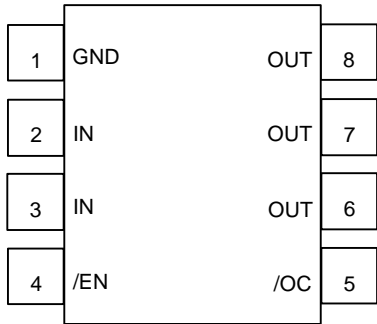
○Product structure : Silicon monolithic integrated circuit ○This product has no designed protection against radioactive rays

Block Diagram

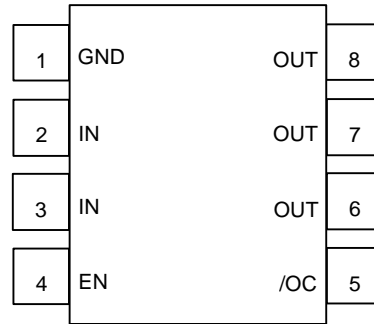


Pin Configurations

BD82000FVJ
(TOP VIEW)



BD82001FVJ
(TOP VIEW)



Pin Description

Pin No.	Symbol	I / O	Pin function
1	GND	-	Ground.
2, 3	IN	-	Power supply input. Input terminal to the power switch and power supply input terminal of the internal circuit. At use, connect each pin outside.
4	EN , /EN	I	Enable input. Power switch on at Low level.(BD82000FVJ) Power switch on at High level.(BD82001FVJ) High level input > 2.0V, Low level input < 0.8V.
5	/OC	O	Error flag output. Low at over-current, thermal shutdown. Open drain output.
6, 7, 8	OUT	O	Power switch output. At use, connect each pin outside.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply voltage	V _{IN}	-0.3 to 6.0	V
Enable input voltage	V _{EN}	-0.3 to 6.0	V
/OC voltage	V _{/OC}	-0.3 to 6.0	V
/OC sink current	I _{S/OC}	below 5	mA
OUT voltage	V _{OUT}	-0.3 to 6.0	V
Storage temperature	T _{STG}	-55 to 150	°C
Power dissipation	P _d	587.5 ^{*1}	mW

*1 Mounted on 70mm*70mm*1.6mm glass-epoxy PCB. Derating : 4.7mW/°C above Ta=25 °C.

Recommended Operating Ratings

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Operating voltage	V _{IN}	2.7	-	5.5	V
Operating temperature	T _{OPR}	-40	-	85	°C

Electrical Characteristics

OBD82000FVJ (Unless otherwise specified V_{IN} = 5.0V, Ta = 25°C)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Operating current	I _{DD}	-	110	160	μA	V _{EN} = 0V , OUT=OPEN
Standby current	I _{STB}	-	0.01	1	μA	V _{EN} = 5V , OUT=OPEN
/EN input voltage	V _{/EN}	2.0	-	-	V	High input
	V _{/EN}	-	-	0.8	V	Low input
/EN input current	I _{/EN}	-1.0	0.01	1.0	μA	V _{/EN} = 0V or V _{/EN} = 5V
/OC output low voltage	V _{/OCL}	-	-	0.5	V	I _{/OC} = 0.5mA
/OC output leak current	I _{L/OC}	-	0.01	1	μA	V _{/OC} = 5V
/OC delay time	T _{/OC}	10	15	20	ms	
On-resistance	R _{ON}	-	70	110	mΩ	I _{OUT} = 500mA
Switch leak current	I _{LSW}	-	-	1.0	μA	V _{EN} = 5V, V _{OUT} = 0V
Current limit threshold	I _{TH}	1.0	1.5	2.0	A	
Short circuit current	I _{SC}	0.7	1.0	1.4	A	V _{OUT} = 0V CL = 47μF (RMS)
Output rise time	T _{ON1}	-	0.8	10	ms	RL = 10Ω
Output turn-on time	T _{ON2}	-	1.1	20	ms	RL = 10Ω
Output fall time	T _{OFF1}	-	5	20	μs	RL = 10Ω
Output turn-off time	T _{OFF2}	-	10	40	μs	RL = 10Ω
UVLO threshold	V _{TUVH}	2.1	2.3	2.5	V	Increasing V _{IN}
	V _{TUVL}	2.0	2.2	2.4	V	Decreasing V _{IN}

Electrical Characteristics - continuedOBD82001FVJ (Unless otherwise specified $V_{IN} = 5.0V$, $T_a = 25^{\circ}C$)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Operating current	I_{DD}	-	110	160	μA	$V_{EN} = 5V$, $OUT=OPEN$
Standby current	I_{STB}	-	0.01	1	μA	$V_{EN} = 0V$, $OUT=OPEN$
EN input voltage	V_{EN}	2.0	-	-	V	High input
	V_{EN}	-	-	0.8	V	Low input
EN input current	I_{EN}	-1.0	0.01	1.0	μA	$V_{EN} = 0V$ or $V_{EN} = 5V$
/OC output low voltage	V_{OCL}	-	-	0.5	V	$I_{OC} = 0.5mA$
/OC output leak current	$I_{L/OC}$	-	0.01	1	μA	$V_{OC} = 5V$
/OC delay time	$T_{/OC}$	10	15	20	ms	
On-resistance	R_{ON}	-	70	110	m Ω	$I_{OUT} = 500mA$
Switch leak current	I_{LSW}	-	-	1.0	μA	$V_{EN} = 0V$, $V_{OUT} = 0V$
Current limit threshold	I_{TH}	1.0	1.5	2.0	A	
Short circuit current	I_{SC}	0.7	1.0	1.4	A	$V_{OUT} = 0V$ $C_L = 47\mu F$ (RMS)
Output rise time	T_{ON1}	-	0.8	10	ms	$R_L = 10\Omega$
Output turn-on time	T_{ON2}	-	1.1	20	ms	$R_L = 10\Omega$
Output fall time	T_{OFF1}	-	5	20	μs	$R_L = 10\Omega$
Output turn-off time	T_{OFF2}	-	10	40	μs	$R_L = 10\Omega$
UVLO threshold	V_{TUVH}	2.1	2.3	2.5	V	Increasing V_{IN}
	V_{TUVHL}	2.0	2.2	2.4	V	Decreasing V_{IN}

Measurement Circuit

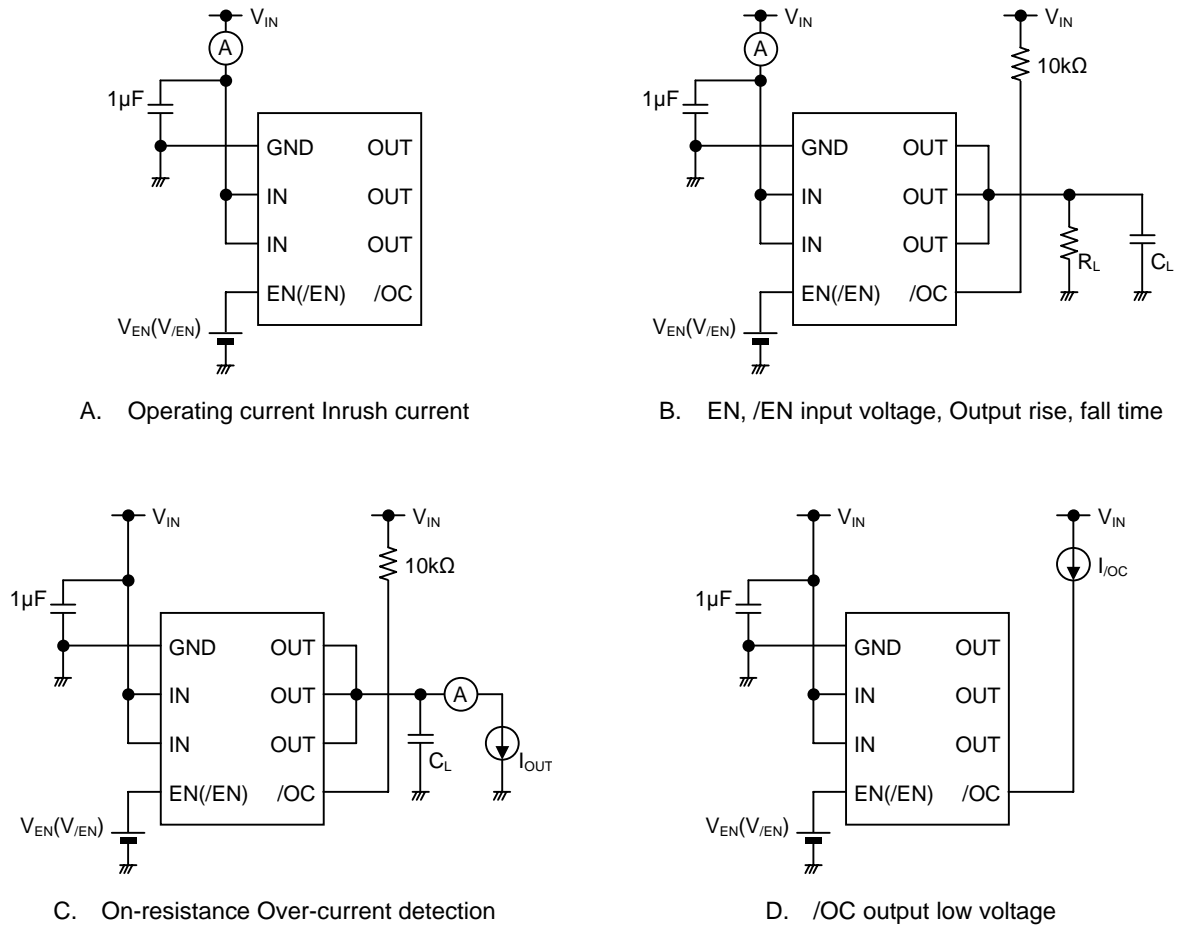


Figure 1. Measurement circuit

Timing Diagram

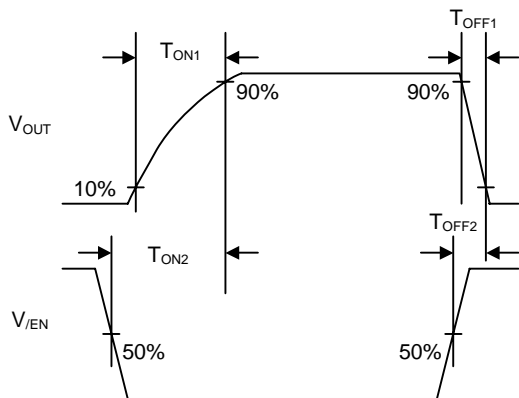


Figure 2. Timing diagram (BD82000FVJ)

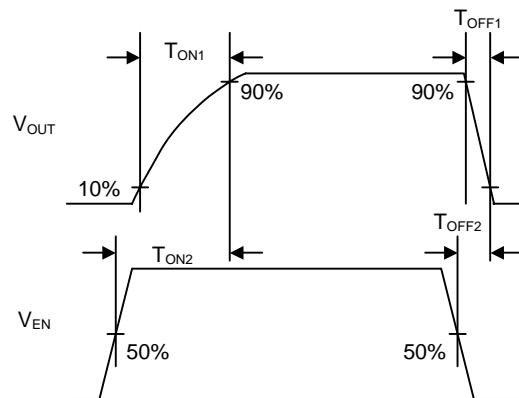


Figure 3. Timing diagram (BD82001FVJ)

Typical Performance Curves

(Reference data)

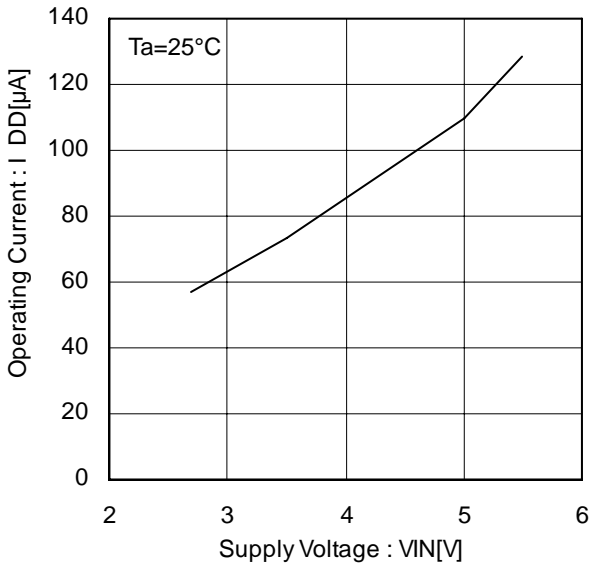


Figure 4. Operating current EN,/EN enable

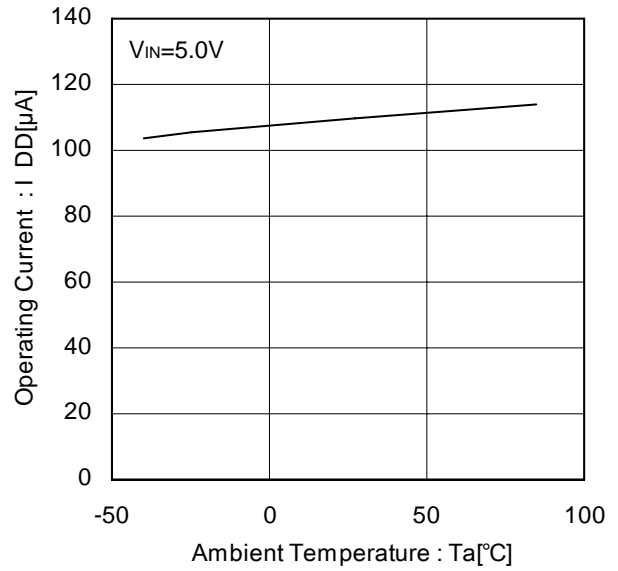


Figure 5. Operating current EN,/EN enable

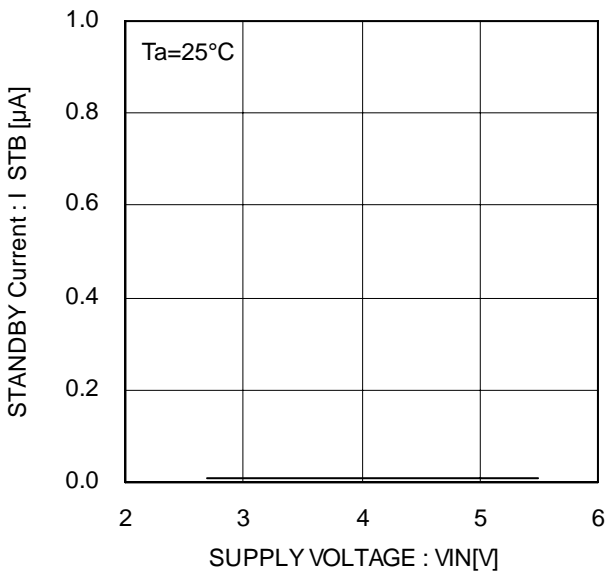


Figure 6. Standby current EN,/EN disable

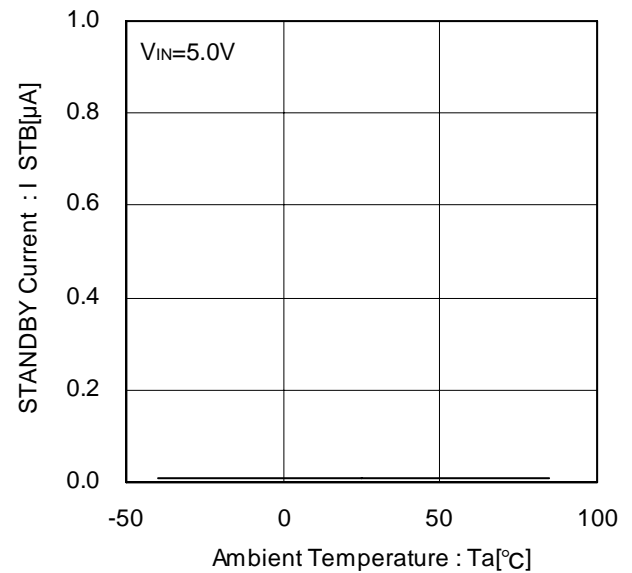


Figure 7. Standby current EN,/EN disable

Typical Performance Curves - continued

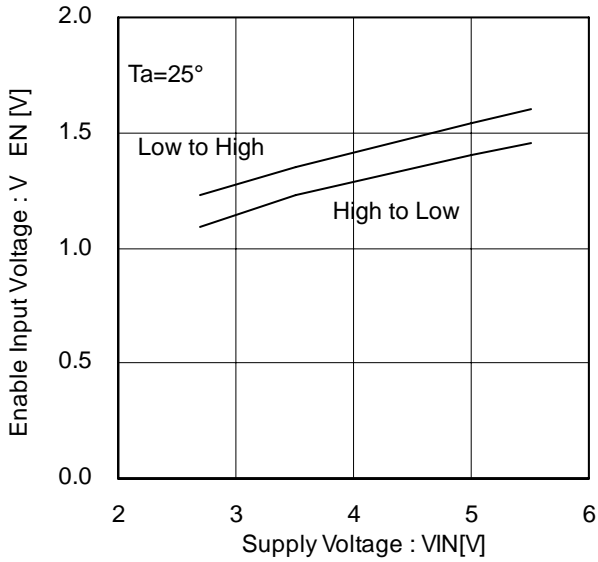


Figure 8. EN, /EN input voltage

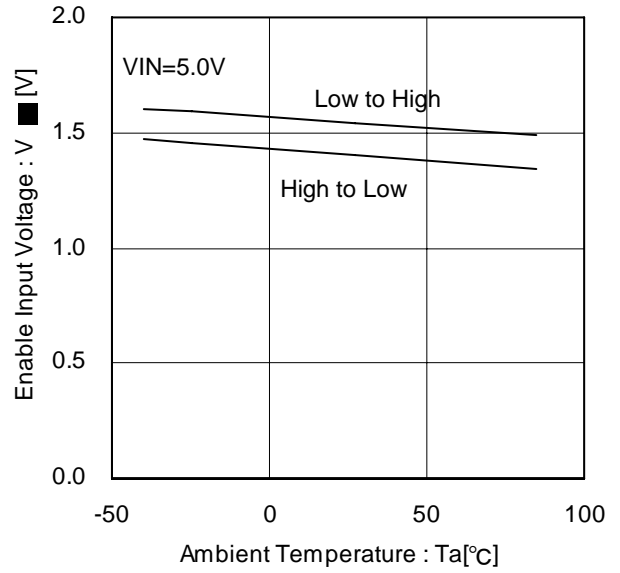


Figure 9. EN, /EN input voltage

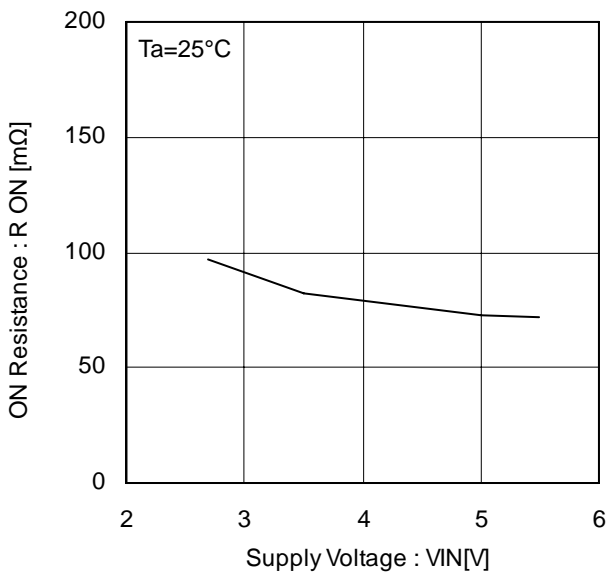


Figure 10. On-resistance

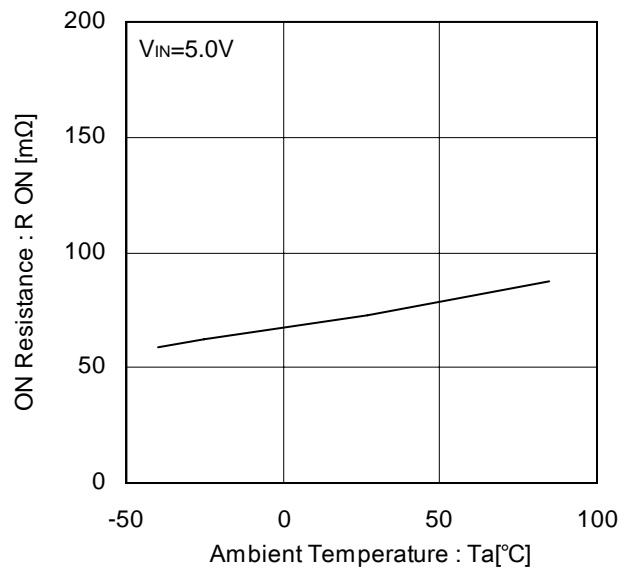


Figure 11. On-resistance

Typical Performance Curves - continued

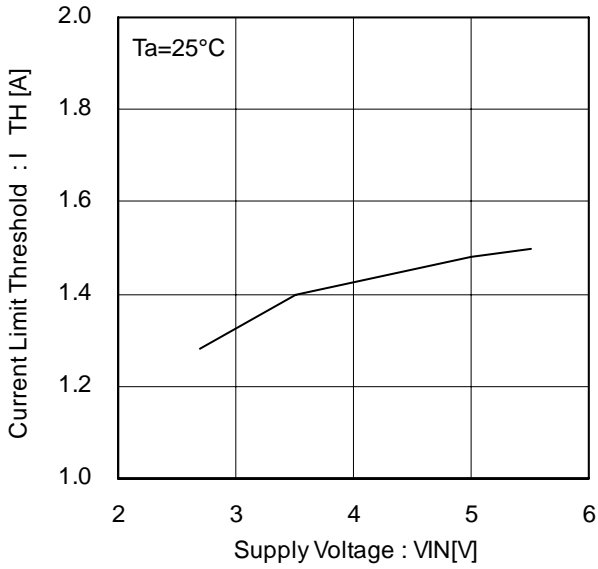


Figure 12. Current limit threshold

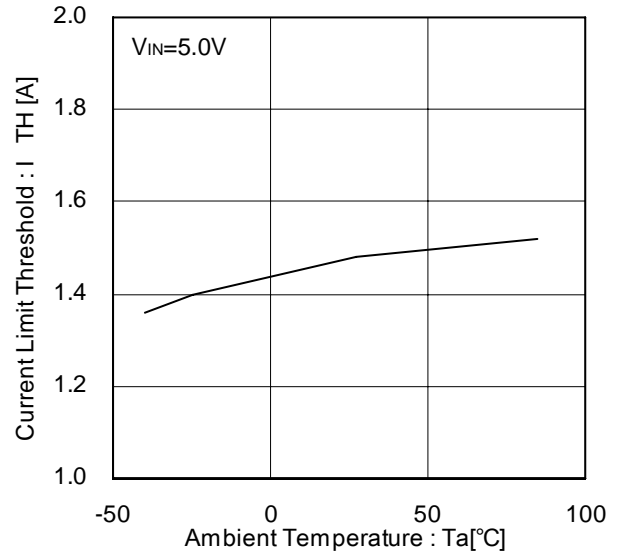


Figure 13. Current limit threshold

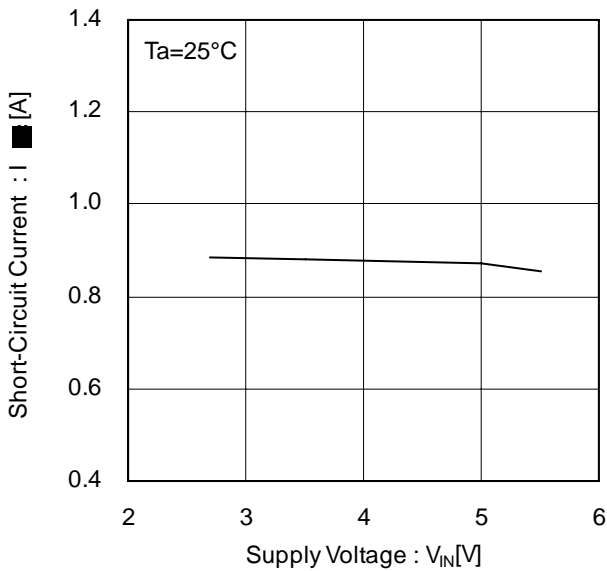


Figure 14. Short circuit current

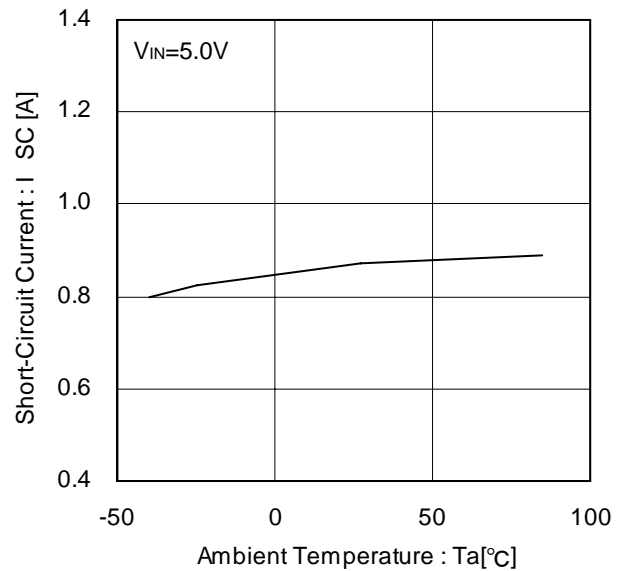


Figure 15. Short circuit current

Typical Performance Curves - continued

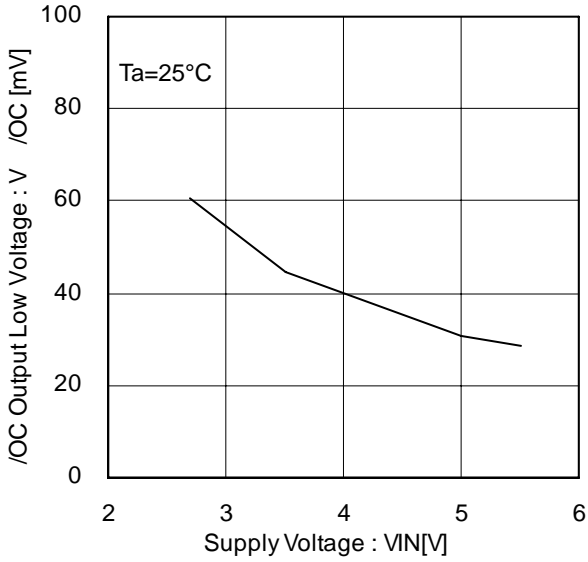


Figure 16. /OC output low voltage

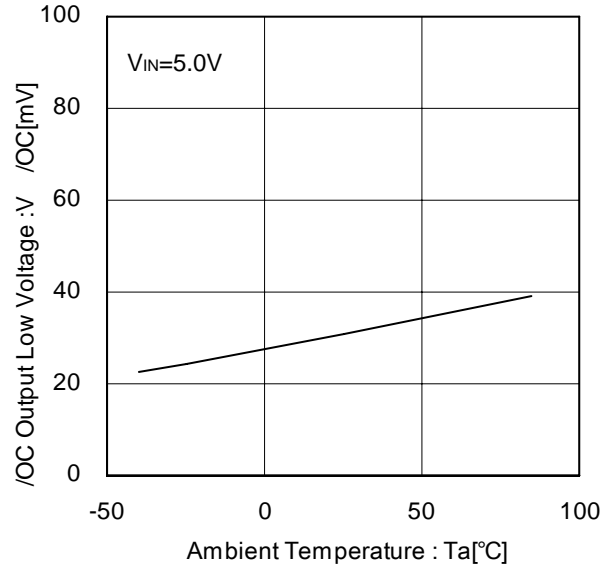


Figure 17. /OC output low voltage

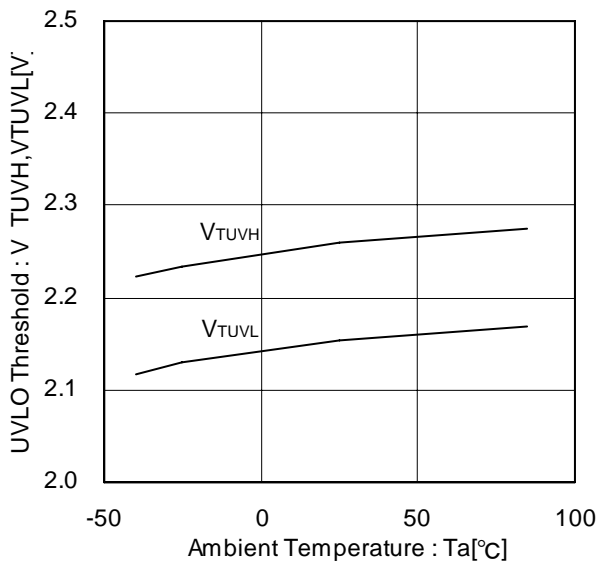


Figure 18. UVLO threshold voltage

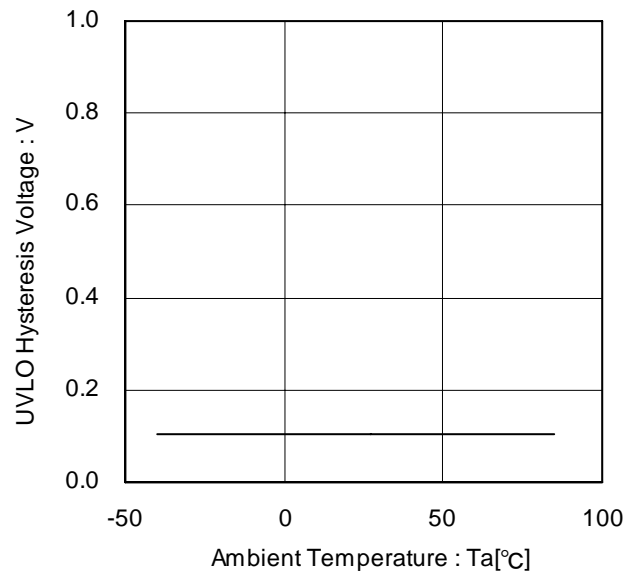


Figure 19. UVLO hysteresis voltage

Typical Performance Curves - continued

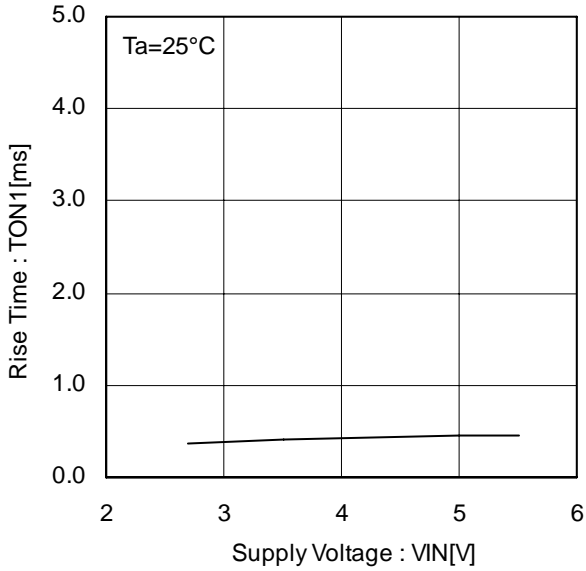


Figure 20. Output rise time

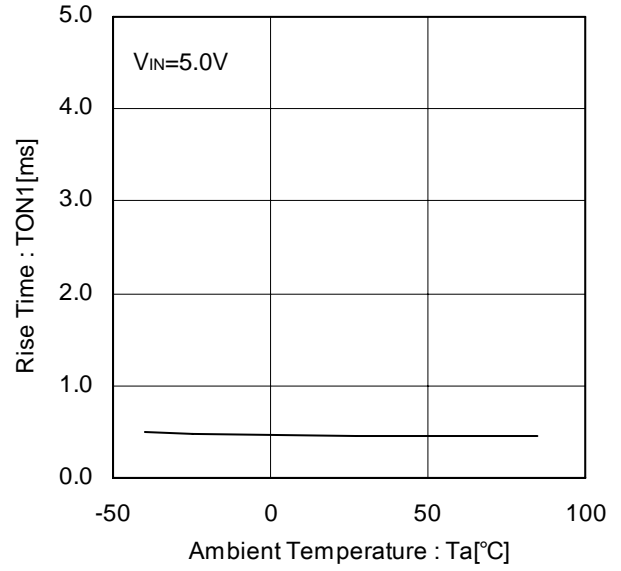


Figure 21. Output rise time

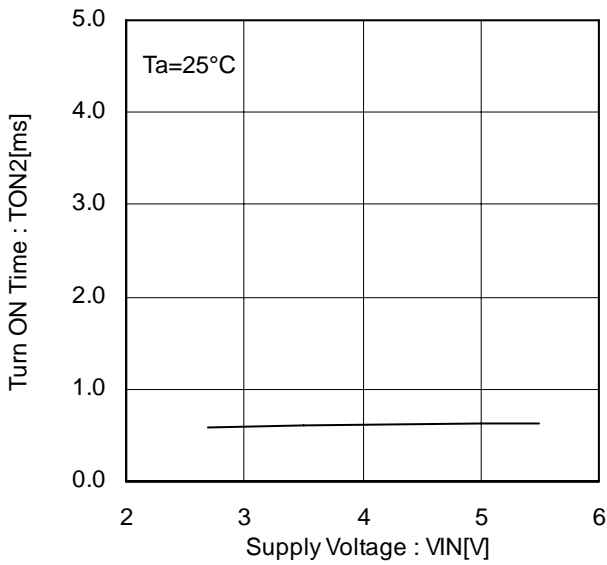


Figure 22. Output turn-on time

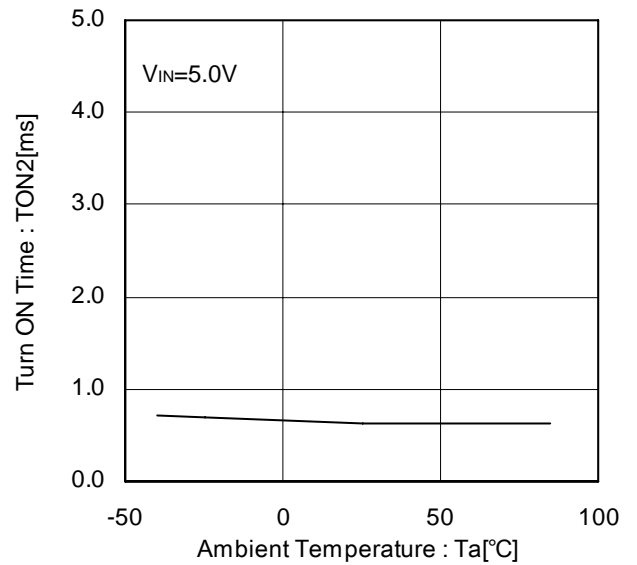


Figure 23. Output turn-on time

Typical Performance Curves - continued

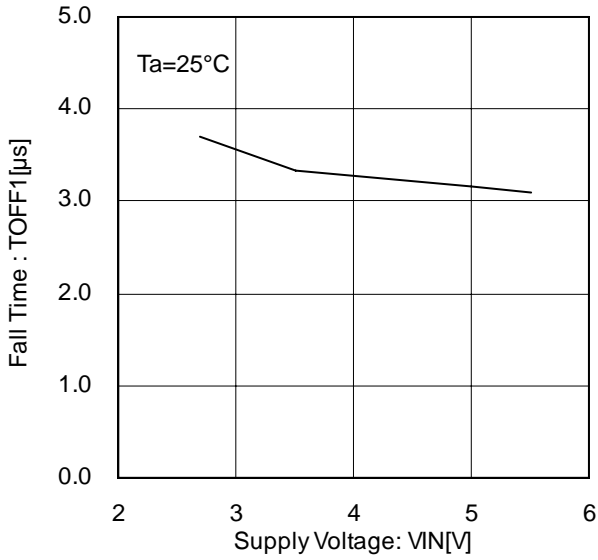


Figure 24. Output fall time

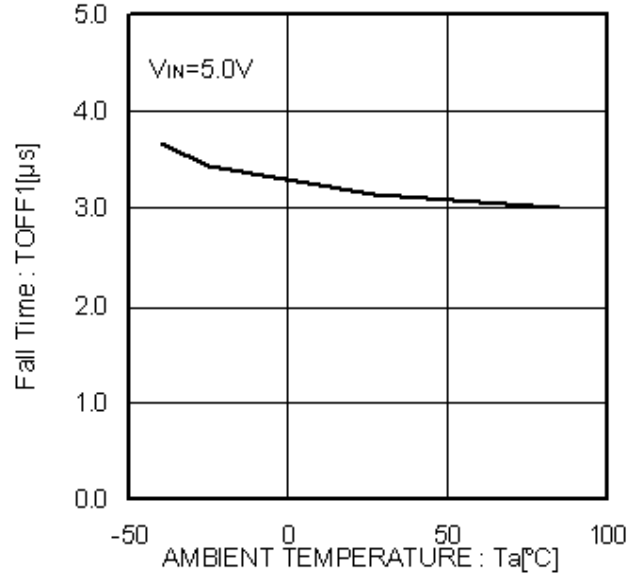


Figure 25. Output fall time

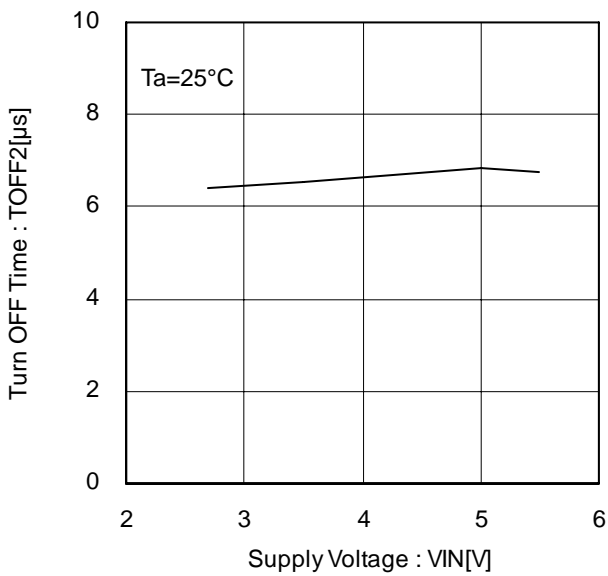


Figure 26. Output turn-off time

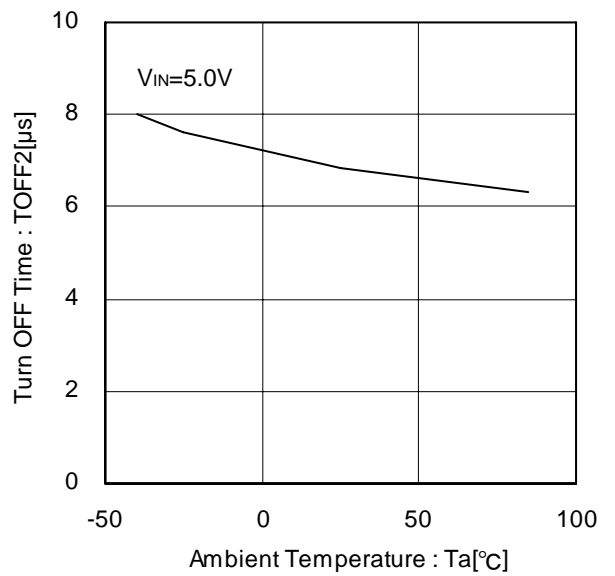


Figure 27. Output turn-off time

Typical Performance Curves - continued

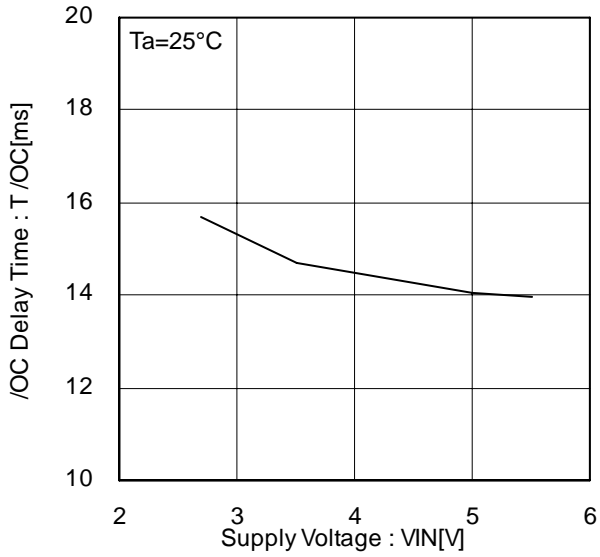


Figure 28. /OC delay time

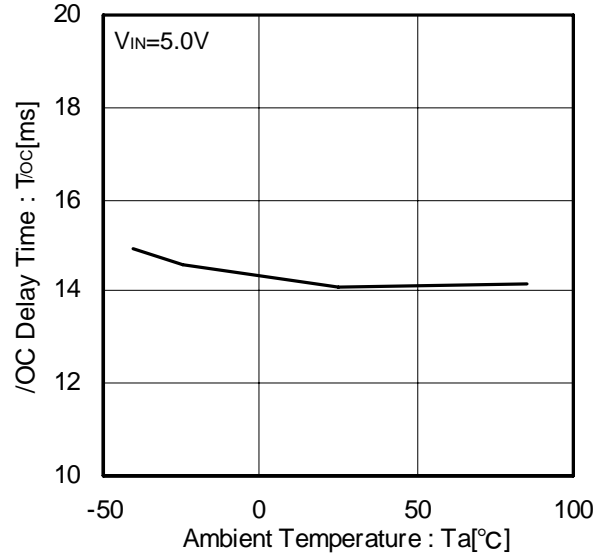


Figure 29. /OC delay time

Typical Wave Forms
(BD82001FVJ)

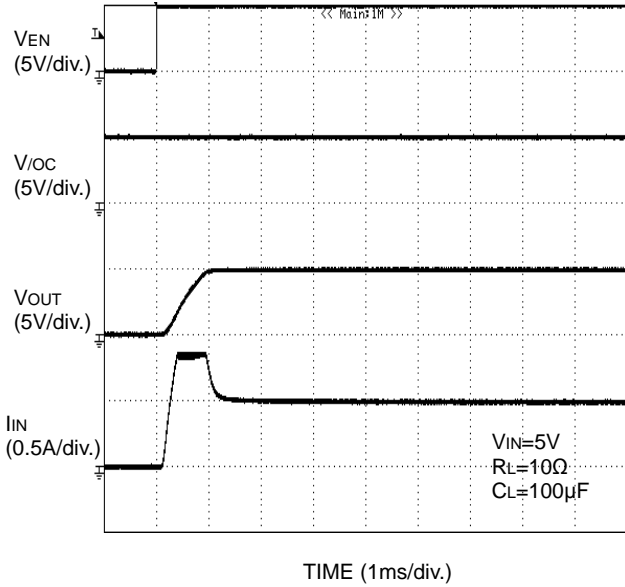


Figure 30. Output rise characteristic

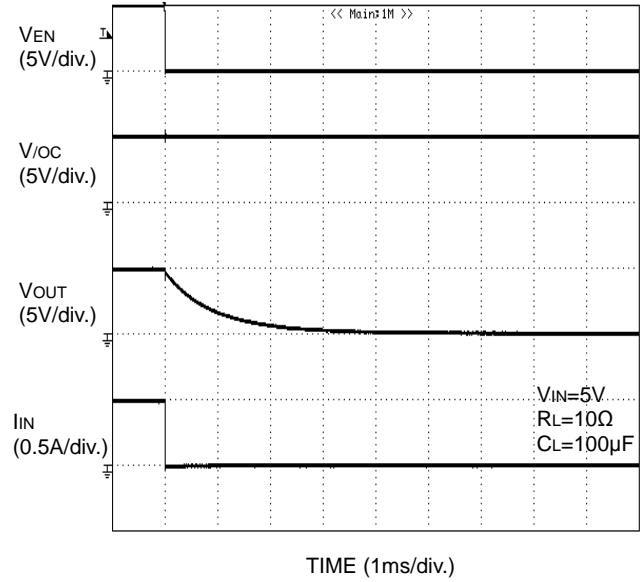


Figure 31. Output rise characteristic

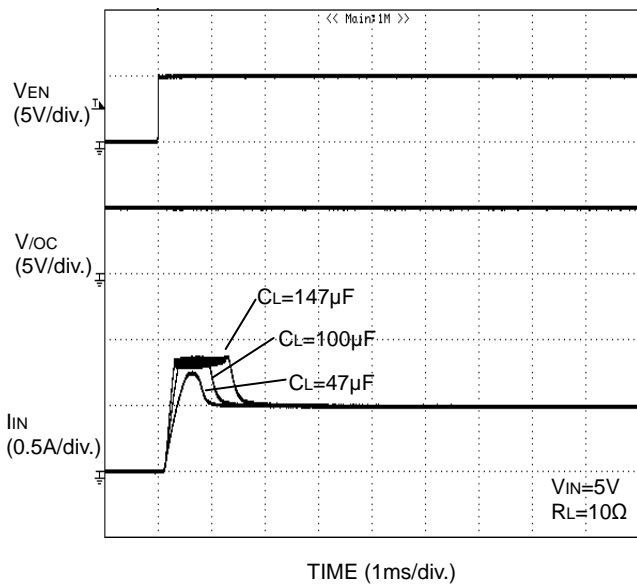


Figure 32. Inrush current response

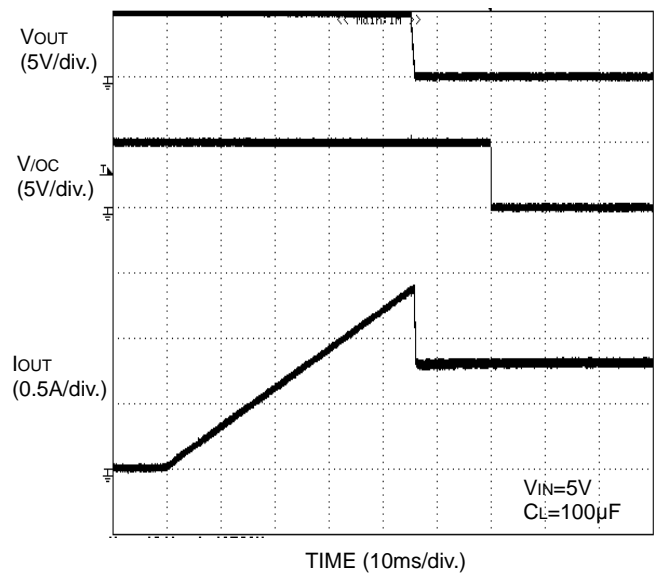


Figure 33. Over-current response ramped load

Typical Wave Forms - continued

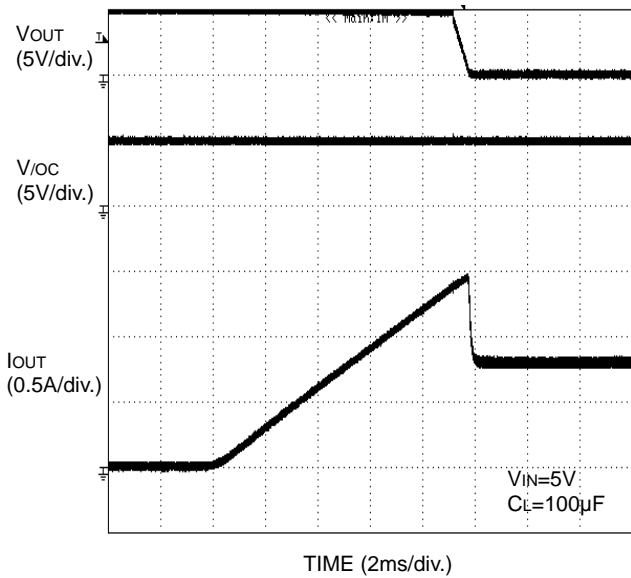


Figure 34. Over-current response ramped load

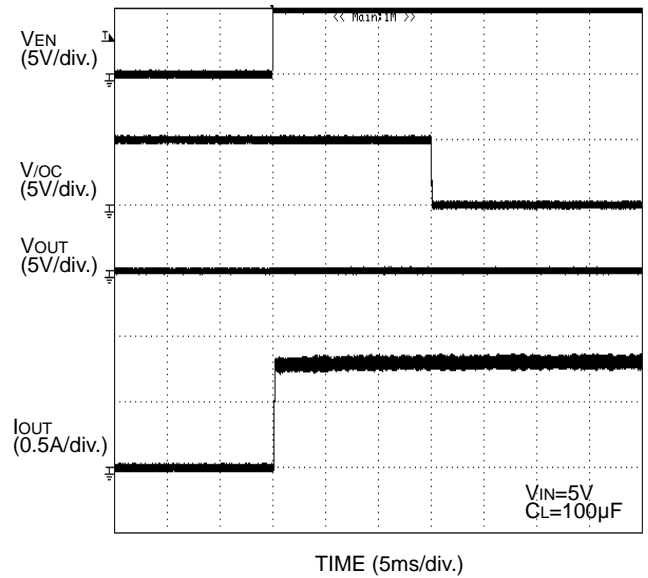


Figure 35. Over-current response enable to shortcircuit

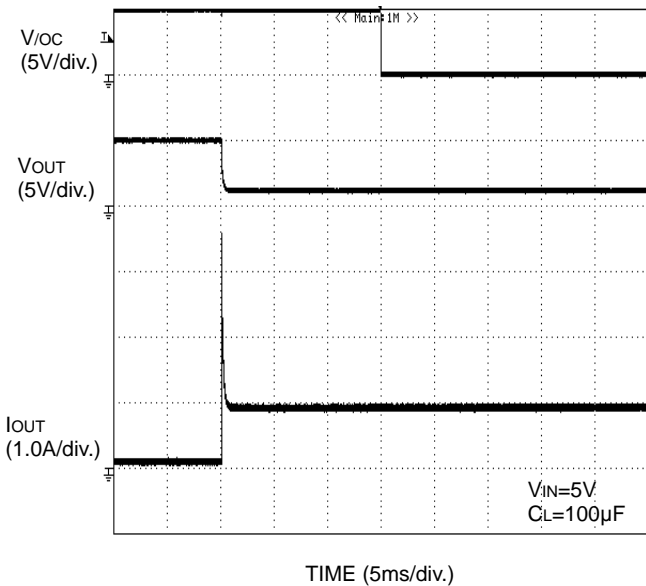


Figure 36. Over-current response 1Ω load connected at enable

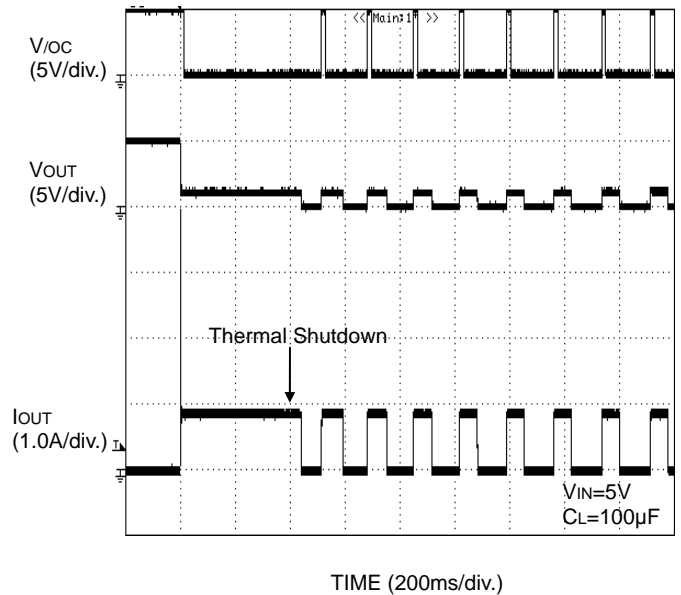


Figure 37. Thermal shutdown 1Ω load connected at enable

Typical Wave Forms - continued

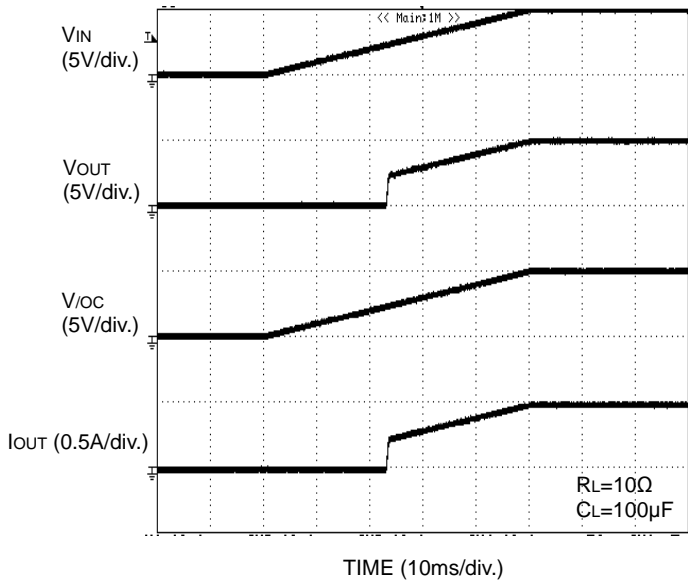


Figure 38. UVLO response increasing V_{IN}

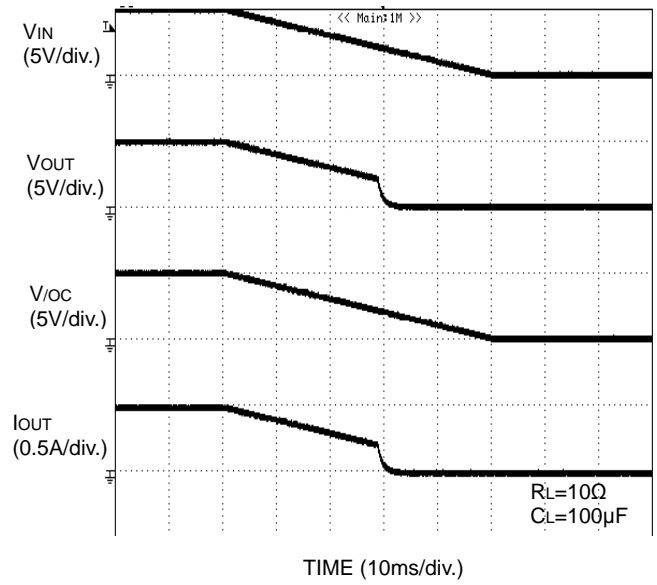
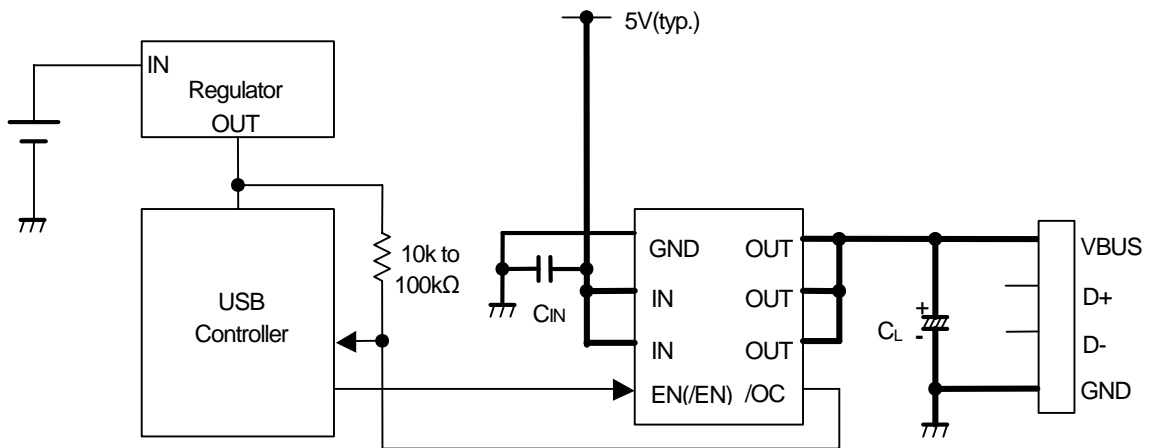


Figure 39. UVLO response decreasing V_{IN}

Typical Application Circuit



Application Information

When excessive current flows owing to output shortcircuit or so, ringing occurs by inductance of power source line to IC, and may cause bad influences upon IC actions. In order to avoid this case, connect a bypass capacitor by IN terminal and GND terminal of IC. 1 μ F or higher is recommended.

Pull up /OC output by resistance 10k Ω to 100k Ω .

Set up value which satisfies the application as C_L.

This system connection diagram doesn't guarantee operating as the application.

The external circuit constant and so on is changed and it uses, in which there are adequate margins by taking into account external parts or dispersion of IC including not only static characteristics but also transient characteristics.

Functional Descriptions

1. Switch operation

IN terminal and OUT terminal are connected to the drain and the source of switch MOSFET respectively. And the IN terminal is used also as power source input to internal control circuit.

When the switch is turned on from EN, /EN control input, IN terminal and OUT terminal are connected by a 70m Ω switch. In on status, the switch is bidirectional. Therefore, when the potential of OUT terminal is higher than that of IN terminal, current flows from OUT terminal to IN terminal.

2. Thermal shutdown circuit (TSD)

If over-current would continue, the temperature of the IC would increase drastically. If the junction temperature were beyond 170°C (typ.) in the condition of over-current detection, thermal shutdown circuit operates and makes power switch turn off and outputs error flag (/OC). Then, when the junction temperature decreases lower than 150°C (typ.), power switch is turned on and error flag (/OC) is cancelled. Unless the fact of the increasing chips temperature is removed or the output of power switch is turned off, this operation repeats.

The thermal shutdown circuit operates when the switch is on (EN, /EN signal is active).

3. Over-current detection (OCD)

The over-current detection circuit limits current (I_{sc}) and outputs error flag (/OC) when current flowing in each switch MOSFET exceeds a specified value. There are three types of response against over-current. The over-current detection circuit works when the switch is on (EN, /EN signal is active).

- 3-1. When the switch is turned on while the output is in shortcircuit status
When the switch is turned on while the output is in shortcircuit status or so, the switch gets in current limit status soon.
- 3-2. When the output shortcircuits while the switch is on
When the output shortcircuits or large capacity is connected while the switch is on, very large current flows until the over-current limit circuit reacts. When the current detection, limit circuit works, current limitation is carried out.
- 3-3. When the output current increases gradually
When the output current increases gradually, current limitation does not work until the output current exceeds the over-current detection value. When it exceeds the detection value, current limitation is carried out.

4. Under-voltage lockout (UVLO)

UVLO circuit prevents the switch from turning on until the V_{IN} exceeds 2.3V (Typ.). If the V_{IN} drops below 2.2V (Typ.) while the switch turns on, then UVLO shuts off the power switch. UVLO has hysteresis of a 100mV (Typ.). Under-voltage lockout circuit works when the switch is on (EN, /EN signal is active).

5. Error flag (/OC) output

Error flag output is N-MOS open drain output. At detection of over-current, thermal shutdown, low level is output.

Over-current detection has delay filter. This delay filter prevents instantaneous current detection such as inrush current at switch on, hot plug from being informed to outside.

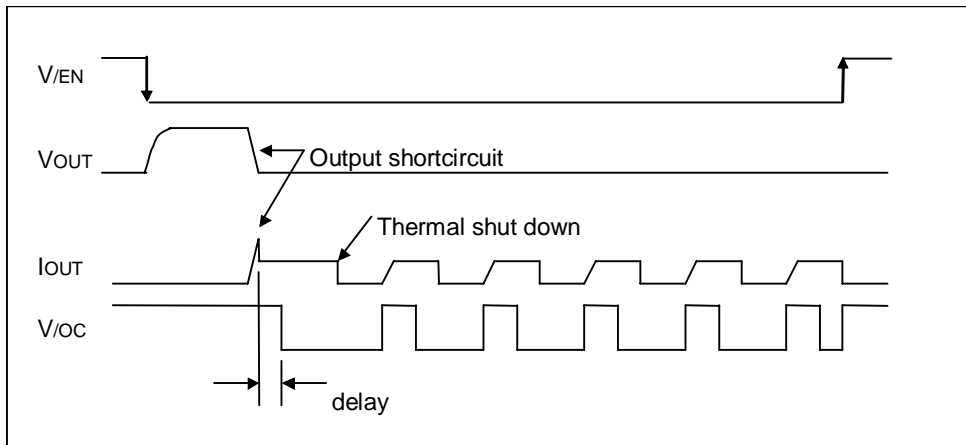


Figure 40. Over-current detection, thermal shutdown timing (BD82000FVJ)

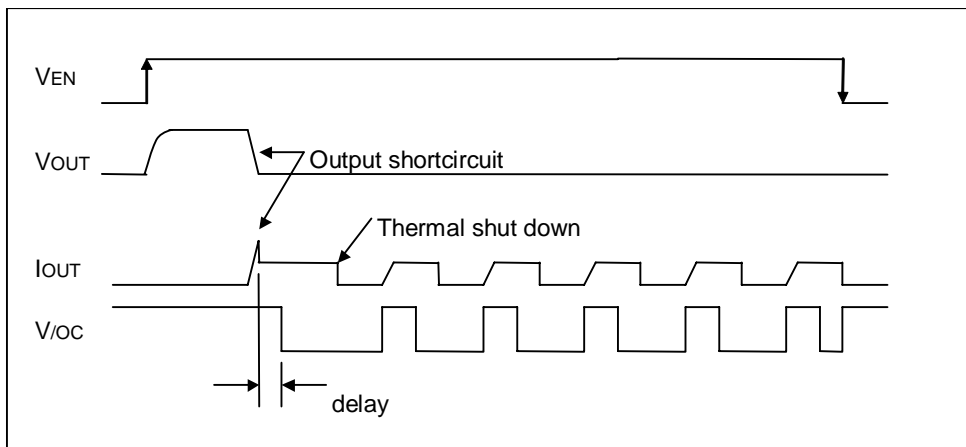


Figure 41. Over-current detection, thermal shutdown timing (BD82001FVJ)

Power Dissipation

(TSSOP-B8J)

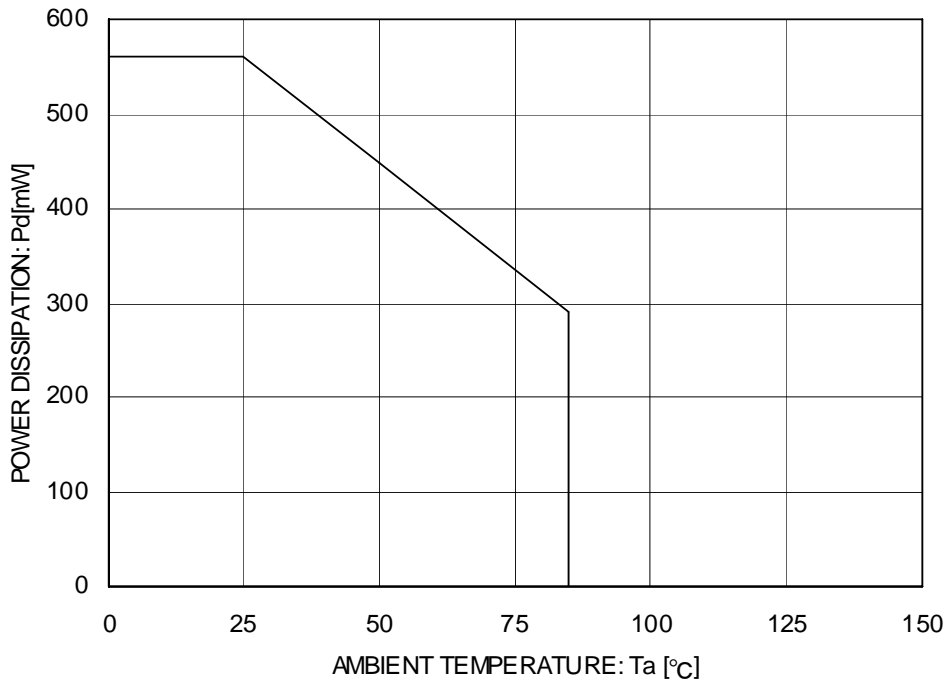


Figure 42. Power dissipation curve (Pd-Ta Curve)

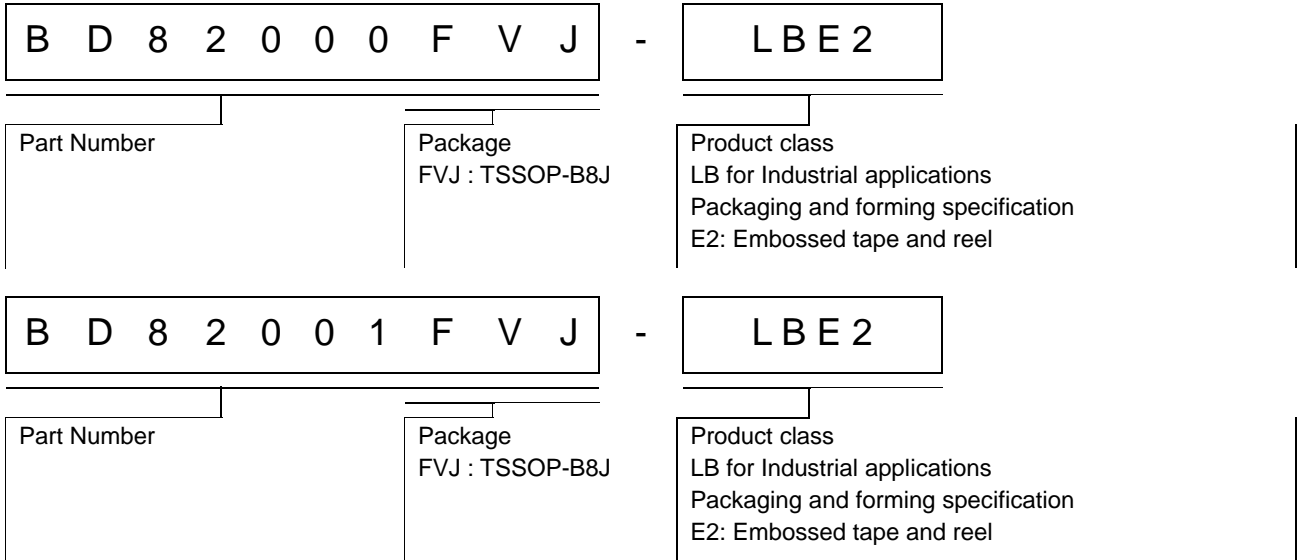
I/O Equivalence Circuit

Symbol	Pin No	Equivalence circuit
EN(/EN)	4	
/OC	5	
OUT	6,7,8	

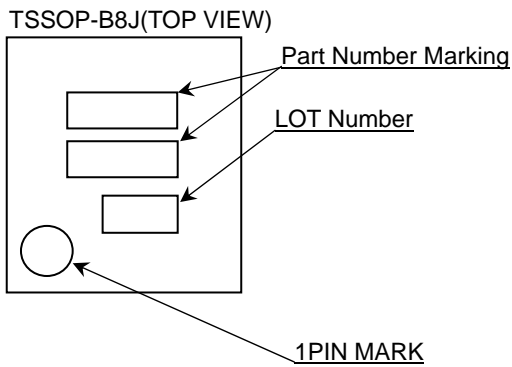
Operational Notes

- (1) Absolute Maximum Ratings
An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.
- (2) Operating conditions
These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.
- (3) Reverse connection of power supply connector
The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.
- (4) Power supply line
Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner. Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.
- (5) GND voltage
Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.
- (6) Short circuit between terminals and erroneous mounting
In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.
- (7) Operation in strong electromagnetic field
Be noted that using ICs in the strong electromagnetic field can malfunction them.
- (8) Inspection with set PCB
On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.
- (9) Input terminals
In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.
- (10) Ground wiring pattern
If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.
- (11) External capacitor
In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.
- (12) Thermal shutdown circuit (TSD)
When junction temperatures become detected temperatures or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit is aimed at isolating the LSI from thermal runaway as much as possible. Do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.
- (13) Thermal design
Perform thermal design in which there are adequate margins by taking into account the power dissipation (Pd) in actual states of use.

Ordering Information



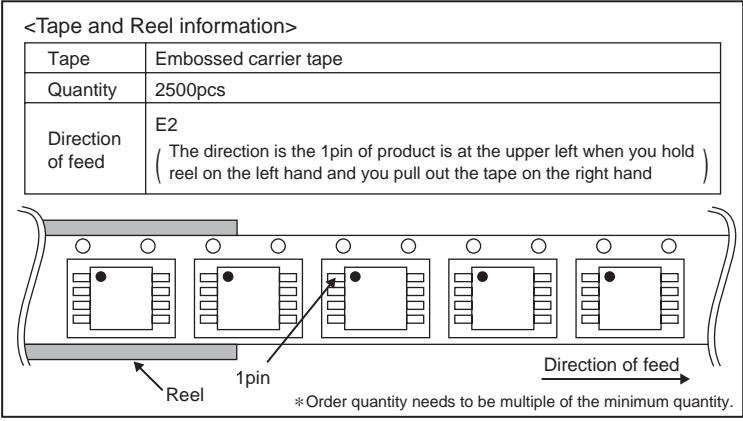
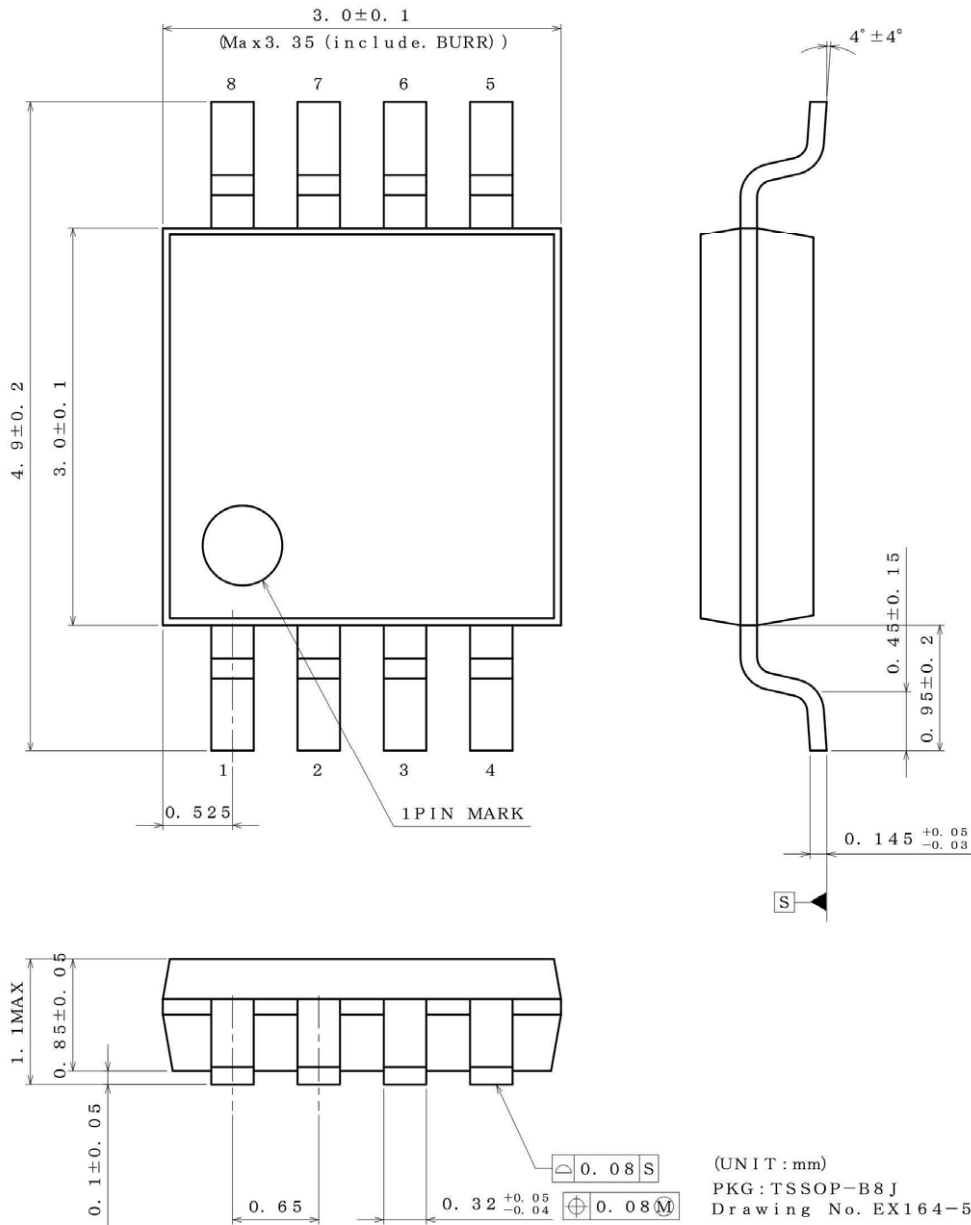
Marking Diagram



Part Number	Part Number Marking
BD82000FVJ	D82000
BD82001FVJ	D82001

Physical Dimension Tape and Reel Information

Package Name	TSSOP-B8J
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Revision History

Date	Revision	Changes
13.Mar.2013	001	New Release
21.Feb.2014	002	Delete sentence "and log life cycle" in General Description and Futures (page 1). Change "Industrial Applications" to "Industrial Equipment" in Applications (page 1). Applied new style ("title" and "Ordering Information").

Notice

Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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